

List of references

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Figure 1

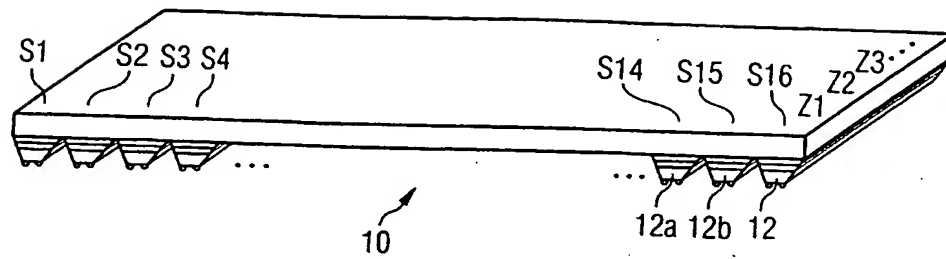
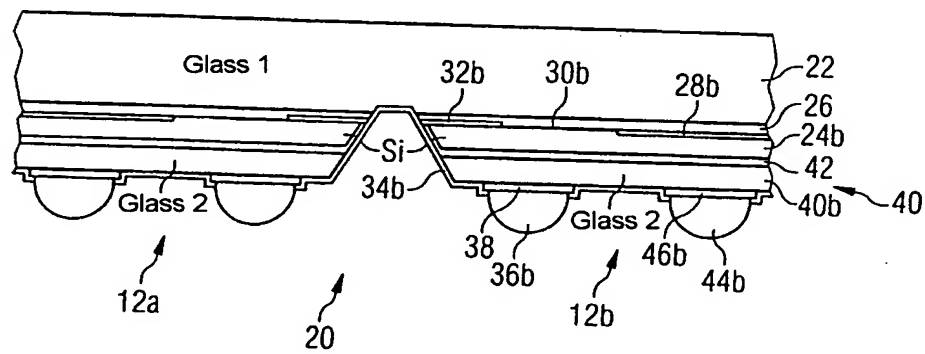


Figure 2



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Figure 3

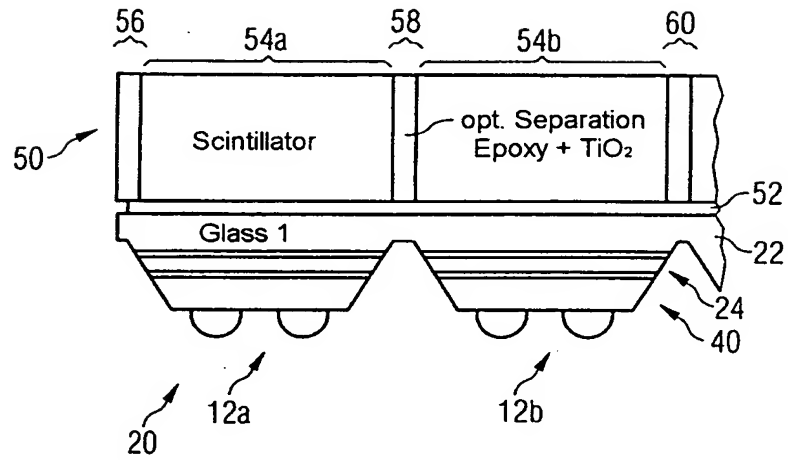
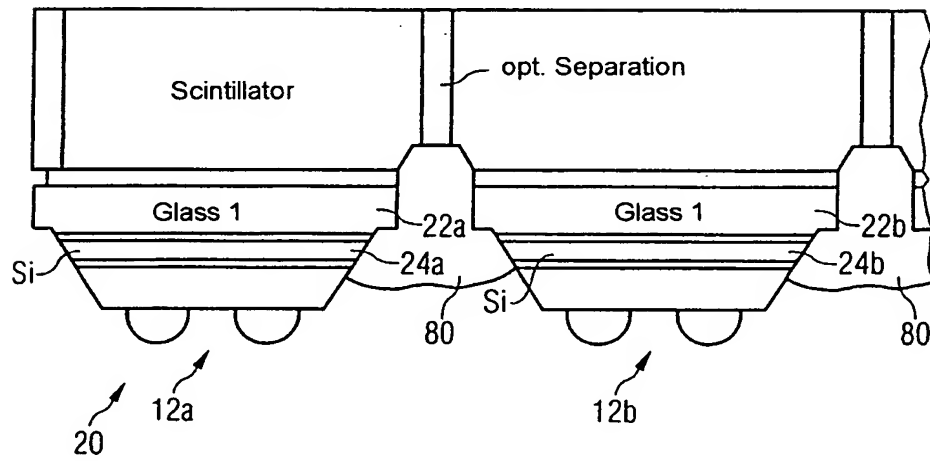


Figure 4



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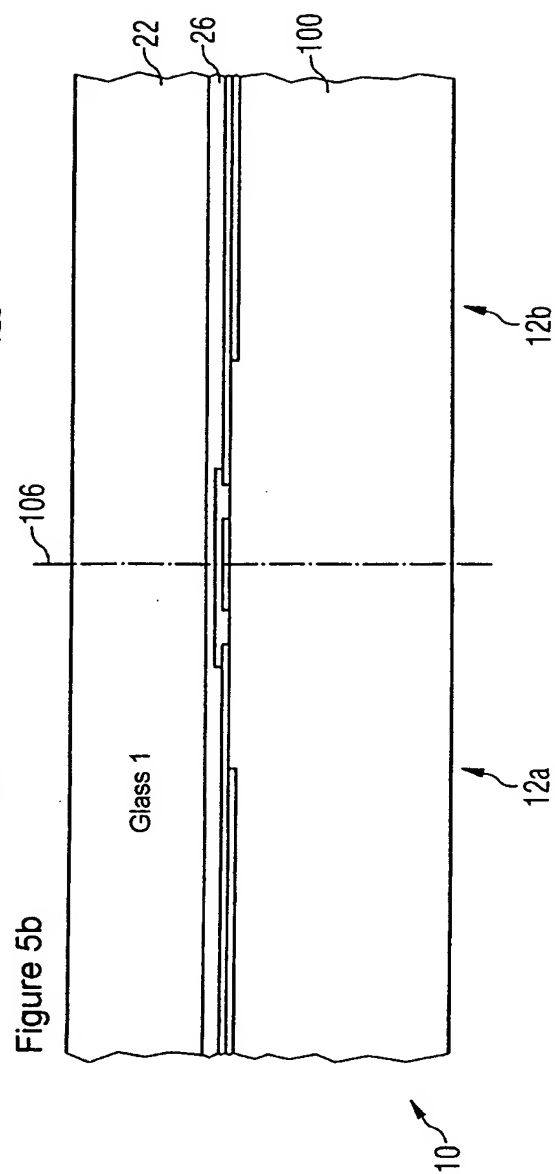
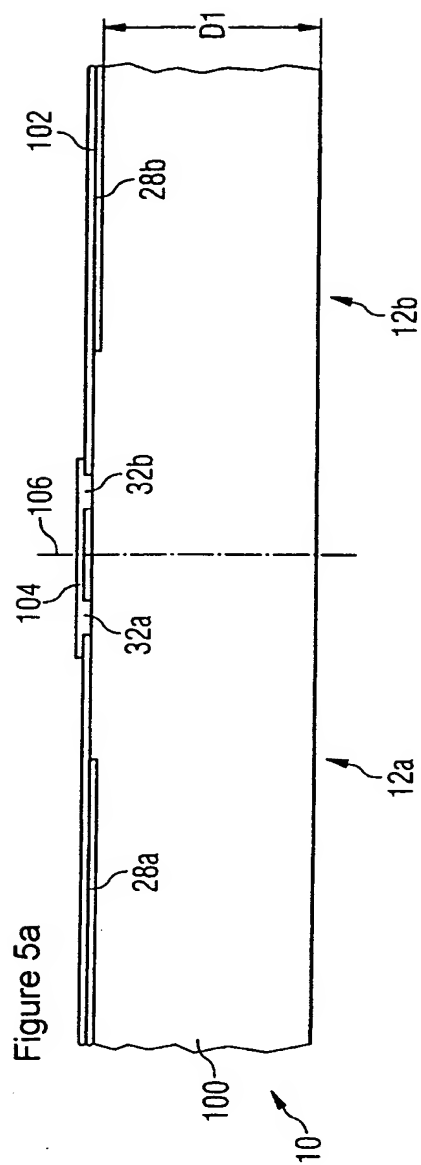


Figure 5C

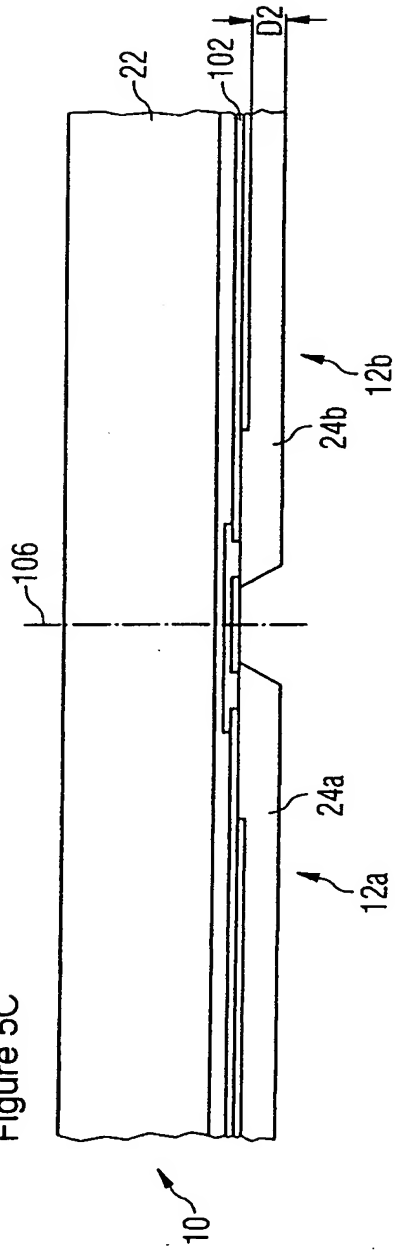
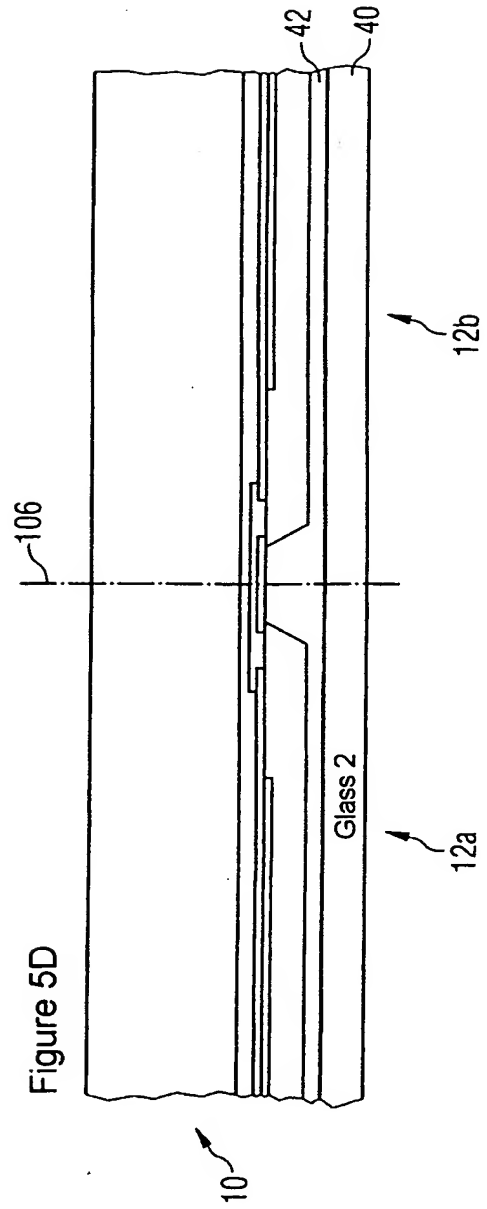


Figure 5D



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Figure 5E

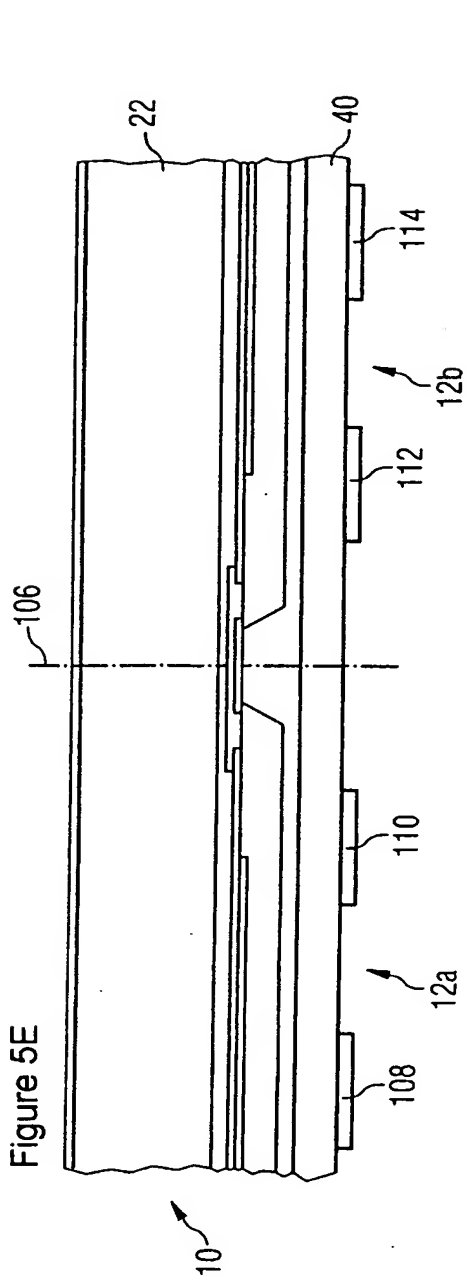


Figure 5F

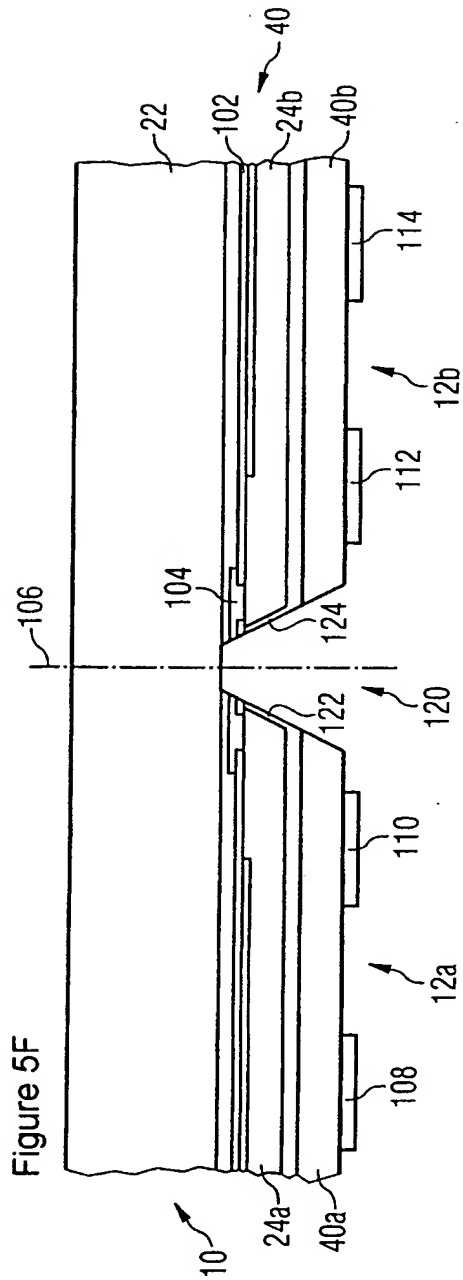


Figure 5G

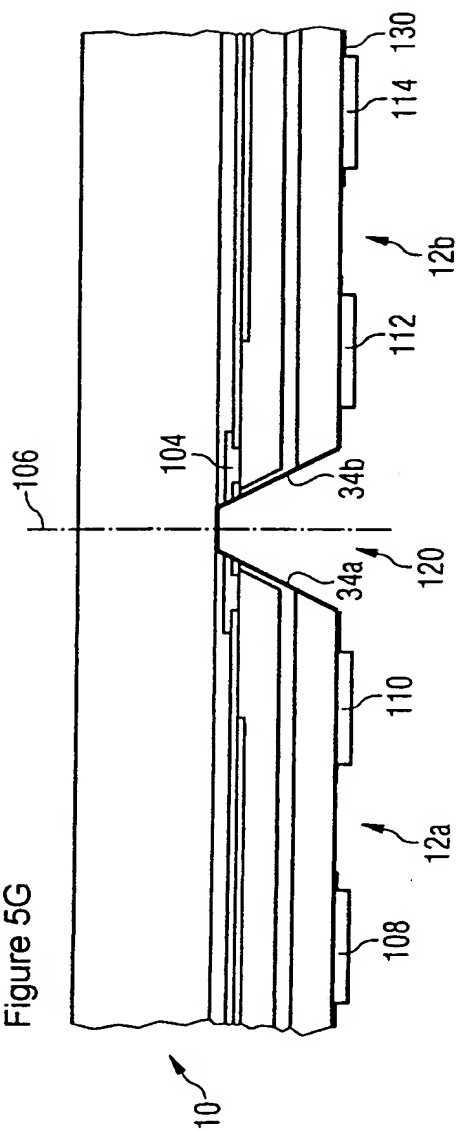
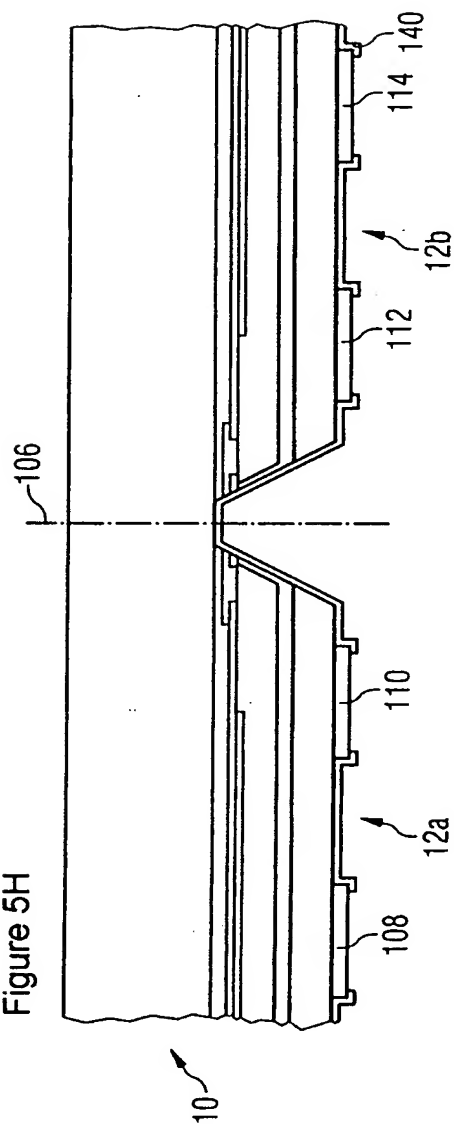


Figure 5H



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